

In re Appln. of Toyoshima et al.  
Application No. Unassigned

**ABSTRACT OF THE DISCLOSURE**

*Subcs 7*

A method of producing a multi-layered wiring board includes exposing and developing a photosensitive resin to form holes having a size; depositing and forming a curable resin on the insulating layer, filling the holes and heating to form a cured thin film of the curable resin on the insulating layer; and removing the curable resin, leaving the cured thin film and producing via-holes having an opening reduced in size from the size of the holes by the cured thin film.

ABSTRACT OF THE DISCLOSURE

Method of producing a multi-layered wiring board comprising the steps of subjecting the photosensitive resin to exposure- and development-treatment to form the holes having a predetermined size and shape; depositing and forming the curable resin to the insulating layer having the holes formed therein in such a manner as to bury the holes, and conducting heat-treatment to form the cured thin film of the curable resin on the surface of the insulating layer; and so removing the curable resin as to leave the cured thin film to obtain the via-holes having the reduced opening size by the cured thin film.

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